

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TIANCHUN YE	03/03/2018
RECEIVING PARTY DATA	
Name:	INSTITUTE OF MICROELECTRONICS, CHINESE ACADEMY OF SCIENCES
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15757601
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NAME OF SUBMITTER:	MATTHEW S. DICKE
SIGNATURE:	/Matthew S. Dicke/
DATE SIGNED:	02/06/2020
Total Attachments: 3	
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ASSIGNMENT

WHEREAS, the undersigned, to wit: Tianchun YE (hereinafter "ASSIGNORS"), are the lawful owners of an invention entitled: **SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF**;

AND WHEREAS, Institute of Microelectronics, Chinese Academy of Sciences (hereinafter "ASSIGNEE"), a corporation duly organized and existing under the laws of China and having its principal office and place of business at No.3 Beitucheng West Road, Chaoyang District, Beijing 100029 China, desires to acquire the entire right, title, and interest therein;

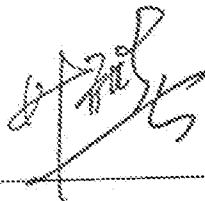
NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, said ASSIGNORS hereby sell, assign, and transfer to ASSIGNEE and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions or improvements that are disclosed in the above identified application and in and to said application (provisional or non-provisional) and all provisional applications, non-provisional applications, utility applications, design applications, divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions or improvements; and in and to all original patents, reissued patents, reexamination certificates, and extensions, that have been or shall be issued in the United States and all foreign countries on said inventions or improvements; and in and to all rights of priority resulting from the filing of said application;

ASSIGNORS hereby agree that said ASSIGNEE may apply for and receive a patent or patents for said inventions or improvements in its own name; and that, when requested at the expense of said ASSIGNEE, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all provisional applications, non-provisional applications, utility applications, design applications, divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions, and all other patent applications on any and all said inventions or improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said ASSIGNEE, its successors, assigns, and representatives all facts known to the undersigned relating to said inventions or improvements and the history thereof; and generally assist said ASSIGNEE, its successors, assigns, or representatives in securing and maintaining proper patent protection for said inventions or improvements and for vesting title to said inventions or improvements, and all applications for patents and all patents on said inventions or improvements, in said ASSIGNEE, its successors, assigns, and legal representatives; and

ASSIGNORS furthermore covenant with said ASSIGNEE, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

ASSIGNORS hereby authorize insertion of the Serial Number and filing date of this application in the following space: Serial No.: 15/757,601 and Filing Date: March 5, 2018.

Signature



Date Signed

03/03/2018

Name: Tianchun YE

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No.3 Beitucheng West Road
Chaoyang District, Beijing 100029 China